

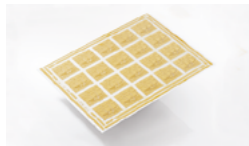


curamik[®]
ENDURANCE

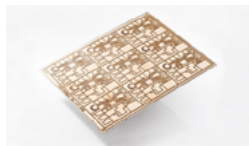
Product Information



curamik®
Power
(Al₂O₃) DBC



curamik®
Power Plus
(HPS) DBC



curamik®
Thermal
(AlN) DBC



curamik®
Endurance
DBC

New

curamik® Endurance extends the field of applications for DBC.

curamik Endurance Substrates

- // curamik Endurance (Al₂O₃)
- // curamik Endurance Plus (HPS)
- // curamik Endurance Thermal (AlN)

Main Applications

- // xEV
- // Industrial (high power)
- // Renewable (high power)
- // Vehicle electrification
- // Mass transit

curamik® Endurance Substrates provide enhanced performance compared to material combinations of the same dimensions. This reliability improvement makes the new substrates well suitable for high power applications, such as in EV/HEV, Vehicle Electrification, Industrial, Renewable and Mass Transit.

Cycling Condition

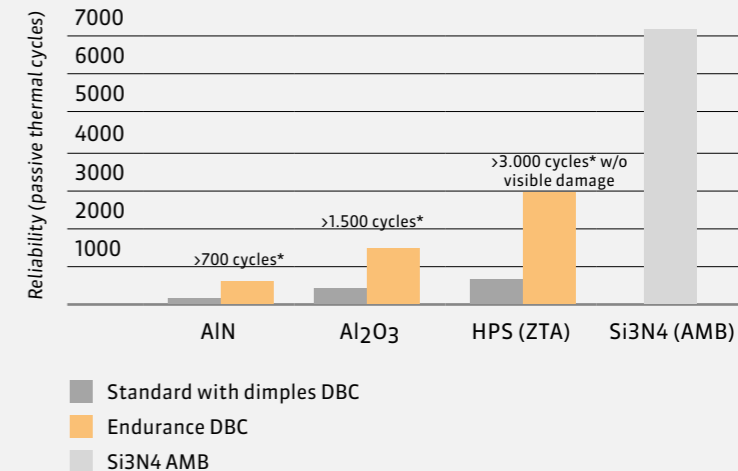
- // -55°C to 150°C
- // 15 min at each plateau

Reference Layout

- // Rogers standard test layout
- // 0.3 mm copper top & bottom
- // 0.32 mm HPS (ZTA)/Al₂O₃/Si₃N₄ ceramic
- // 0.63 mm AlN

Thermal cycle tests show that curamik® Endurance substrates have an extraordinary increased lifetime compared to its alternative standard DBC substrates with dimples (AlN, Al₂O₃, HPS (ZTA)).

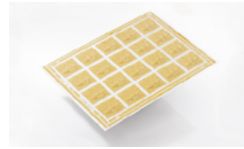
Enhanced reliability compared to material combinations of the same dimensions.



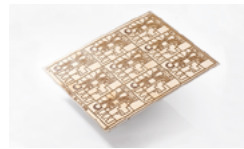
*Depending on customer layout



curamik® Power (Al₂O₃) DBC



curamik® Power Plus (HPS) DBC



curamik® Thermal (AlN) DBC



curamik® Endurance DBC

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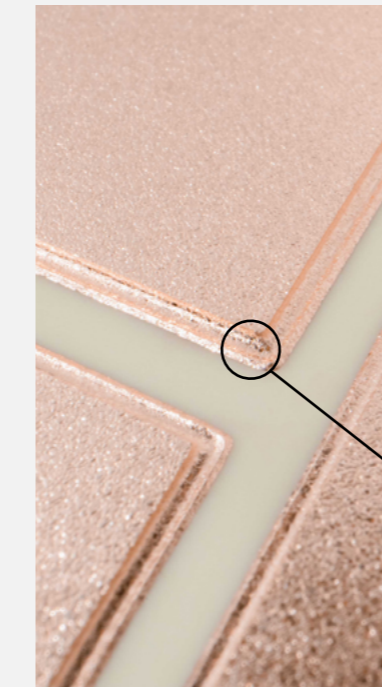
Properties

- // Cu-Thickness: 0.3 mm
- // Ceramic Types: Al₂O₃, HPS (ZTA), AlN
- // Thermal conductivity: 24, 26, 170 W/mK
- // Ceramic Thicknesses: acc. Std. Design Rules

Material	Al ₂ O ₃	HPS (ZTA)	AlN
ceramik thickness (in mm)			
0.25	✓	✓	
0.32	✓	✓	
0.38	✓		
0.5	✓		
0.63	✓		✓
1.00	✓		✓

Al₂O₃ other thicknesses on request
 HPS (ZTA) ZrO₂ toughened Al₂O₃ with 9% content
 AlN other thicknesses on request

Known material and combinations for easy implementation.



To achieve the increase in reliability, Rogers adjusted the design of the copper sidewall to gain the perfect stress release. The current available material combinations are all based on a 0.3mm copper thickness. The ceramic types Al₂O₃, HPS (ZTA) and AlN can be chosen by referencing our curamik® Ceramic Substrates - DBC Technology design rules.

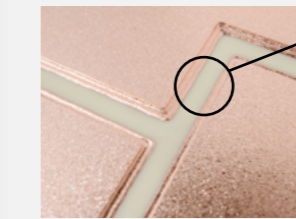


Flat walls consume ~40% less surface than dimples.

Standard Etch Walls and Dimples



New Flat Etch Walls



Milestones

Samples – available
 Design Rules – available
 SOP – Q4

Better Price and Performance Ratio

More Usable Area

Higher Reliability



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www.curamik.com

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